501888163 04/13/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jin-Mu YIN	04/10/2012
Shyh-Wei WANG	04/10/2012
Yen-Ming CHEN	04/10/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13446769

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	T5057-732
NAME OF SUBMITTER:	Randy A. Noranbrock

Total Attachments: 1

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PATENT

REEL: 028045 FRAME: 0946

OF \$40.00 134467

Docket No. T5057-732 TSMC2011-1533

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Jin-Mu YIN
- 2) SHYH- Wei WANG
- 3) Yen-Ming CHEN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

FABRICATION METHODS OF INTEGRATED SEMICONDUCTOR STRUCTURE

(a)	for which an application for United States Letters Patent was filed on States Patent Application No. $\frac{2012-4-13}{13/446,769}$; or	, and identified by United
(b)	for which an application for United States Letters Patent was executed on,	

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Jin Mu Yin	2012/4/10.
Name: Jin-Mu YIN	Date:
2) Shyh-Wei Wang	04/10 112
Name: Shyh-Wei WANG	Date:
3) Yen-May Chen,	04/10 112
Name: Yen-Ming CHEN	Date:

PATENT REEL: 028045 FRAME: 0947

RECORDED: 04/13/2012